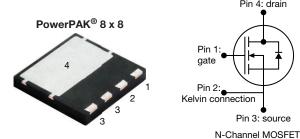




E Series Power MOSFET

Pin 4: drain



| PRODUCT SUMMARY | | | | | |
|---------------------------------------|------------------------------|-----|--|--|--|
| V_{DS} (V) at T_J max. | 650 | | | | |
| R _{DS(on)} typ. (Ω) at 25 °C | V _{GS} = 10 V 0.085 | | | | |
| Q _g max. (nC) | 53 | | | | |
| Q _{gs} (nC) | 11 | | | | |
| Q _{gd} (nC) | 1 | 3 | | | |
| Configuration | Sin | gle | | | |

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- · Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- · Kelvin connection for reduced gate noise
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- Server and telecom power supplies
- · Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

| ORDERING INFORMATION | |
|---------------------------------|--------------------|
| Package | PowerPAK 8 x 8 |
| Lead (Pb)-free and halogen-free | SiHH100N60E-T1-GE3 |

| PARAMETER | | | SYMBOL | LIMIT | UNIT | |
|---|-------------------------|---|-----------------------------------|-------------|------|--|
| Drain-source voltage | | | V _{DS} | 600 | V | |
| Gate-source voltage | | | V_{GS} | ± 30 | 7 ° | |
| Continuous drain current (T _J = 150 °C) | V at 10 V | T _C = 25 °C T _C = 100 °C | , | 28 | | |
| | V _{GS} at 10 V | T _C = 100 °C | I _D | 18 | A | |
| Pulsed drain current ^a | | | I _{DM} | 63 | | |
| Linear derating factor | | | | 1.38 | W/°C | |
| Single pulse avalanche energy b | | | E _{AS} | 127 | mJ | |
| Maximum power dissipation | | | P _D | 174 | W | |
| Operating junction and storage temperature r | ange | | T _J , T _{stg} | -55 to +150 | °C | |
| Drain-source voltage slope $T_J = 125 ^{\circ}\text{C}$ | | | d. //d+ | 100 | 1 | |
| Reverse diode dv/dt ^c | | | dv/dt | 50 | V/ns | |

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_q = 25 Ω , I_{AS} = 3.0 A
- c. $I_{SD} \le I_D$, di/dt = 120 A/ μ s, starting $T_J = 25$ °C



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| THERMAL RESISTANCE RATINGS | | | | | |
|----------------------------------|------------|------|------|------|--|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT | |
| Maximum junction-to-ambient | R_{thJA} | 40 | 42 | °C/W | |
| Maximum junction-to-case (drain) | R_{thJC} | 0.55 | 0.72 | G/VV | |

| PARAMETER | SYMBOL | TES | T CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|---|-----------------------|---|---|------|-------|----------|------|
| Static | | - | | | | | |
| Drain-source breakdown voltage | V _{DS} | V _{GS} = | = 0 V, I _D = 250 μA | 600 | _ | - | V |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | Referenc | e to 25 °C, I _D = 1 mA | - | 0.55 | - | V/°C |
| Gate-source threshold voltage (N) | V _{GS(th)} | V _{DS} = | - V _{GS} , I _D = 250 μA | 3.0 | - | 5.0 | V |
| | | , | V _{GS} = ± 20 V | - | - | ± 100 | nA |
| Gate-source leakage | I _{GSS} | , | V _{GS} = ± 30 V | - | - | ± 1 | μΑ |
| | _ | V _{DS} = | V _{DS} = 600 V, V _{GS} = 0 V | | - | 1 | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} = 480 V | ', V _{GS} = 0 V, T _J = 125 °C | - | = | 10 | μA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} = 10 V | I _D = 13.5 A | - | 0.085 | 0.100 | Ω |
| Forward transconductance ^a | 9 _{fs} | V _{DS} : | = 8 V, I _D = 13.5 A | - | 12 | - | S |
| Dynamic | | | | | | | |
| Input capacitance | C _{iss} | | V _{GS} = 0 V, | - | 1850 | - | |
| Output capacitance | C _{oss} | Τ, | $V_{DS} = 100 \text{ V},$ | - | 83 | - | |
| Reverse transfer capacitance | C _{rss} | 1 | f = 1 MHz | - | 6 | - | |
| Effective output capacitance, energy related ^a | C _{o(er)} | V _{DS} = 0 V to 480 V, V _{GS} = 0 V | | - | 64 | - | pF |
| Effective output capacitance, time related ^b | C _{o(tr)} | | | - | 410 | - | |
| Total gate charge | Q_g | | | - | 35 | 53 | |
| Gate-source charge | Q_{gs} | V _{GS} = 10 V | $I_D = 13.5 \text{ A}, V_{DS} = 480 \text{ V}$ | - | 11 | - | nC |
| Gate-drain charge | Q _{gd} | | | - | 13 | - | |
| Turn-on delay time | t _{d(on)} | | | - | 26 | 52 | |
| Rise time | t _r | $V_{DD} = 480 \text{ V}, I_D = 13.5 \text{ A},$ | | - | 54 | 81 | |
| Turn-off delay time | t _{d(off)} | | = 10 V, $R_g = 9.1 \Omega$ | - | 41 | 82 | ns |
| Fall time | t _f | | | - | 41 | 82 | |
| Gate input resistance | R_g | f = 1 | MHz, open drain | 0.3 | 0.6 | 1.2 | Ω |
| Drain-Source Body Diode Characteristic | s | | | | | | |
| Continuous source-drain diode current | I _S | MOSFET symbol showing the integral reverse p - n junction diode | | - | - | 28 | |
| Pulsed diode forward current | I _{SM} | | | - | - | 63 | A |
| Diode forward voltage | V _{SD} | T _J = 25 °C | , I _S = 13.5 A, V _{GS} = 0 V | - | - | 1.2 | V |
| Reverse recovery time | t _{rr} | | | - | 345 | 690 | ns |
| Reverse recovery charge | Q _{rr} | | $^{\circ}$ C, $I_F = I_S = 13.5 \text{ A},$ | - | 5.0 | 10 | μC |
| Reverse recovery current | I _{RRM} | | 100 A/ μ s, V _R = 25 V | _ | 24 | <u> </u> | Α |

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

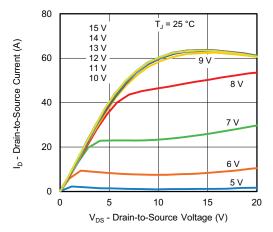


Fig. 1 - Typical Output Characteristics

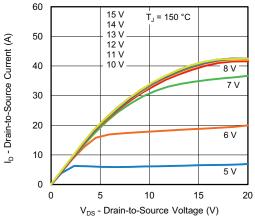


Fig. 2 - Typical Output Characteristics

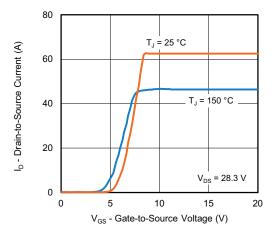


Fig. 3 - Typical Transfer Characteristics

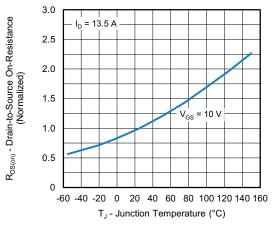


Fig. 4 - Normalized On-Resistance vs. Temperature

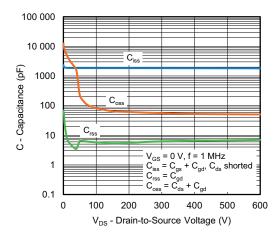


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

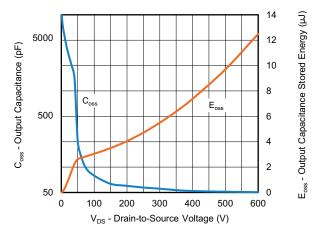


Fig. 6 - Coss and Eoss vs. VDS



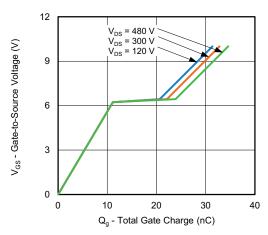


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

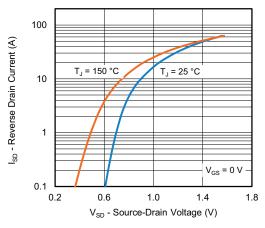


Fig. 8 - Typical Source-Drain Diode Forward Voltage

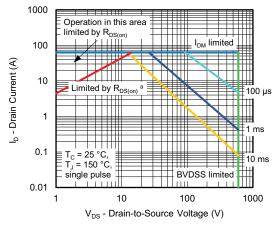


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

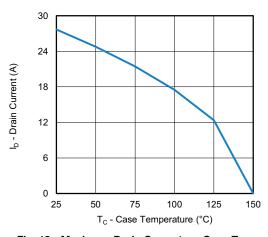


Fig. 10 - Maximum Drain Current vs. Case Temperature

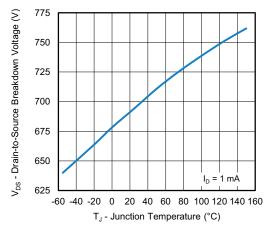


Fig. 11 - Temperature vs. Drain-to-Source Voltage



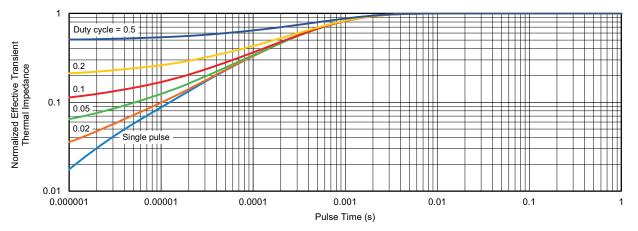


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

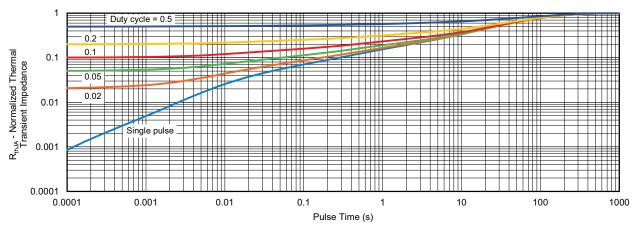


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

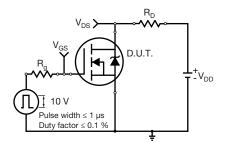


Fig. 14 - Switching Time Test Circuit

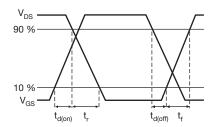


Fig. 15 - Switching Time Waveforms



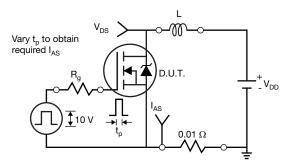


Fig. 16 - Unclamped Inductive Test Circuit

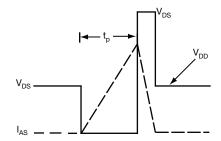


Fig. 17 - Unclamped Inductive Waveforms

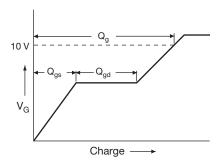


Fig. 18 - Basic Gate Charge Waveform

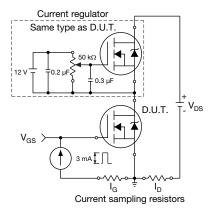
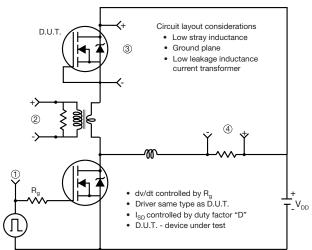


Fig. 19 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



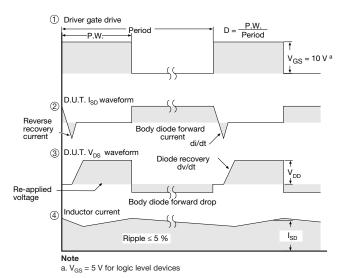


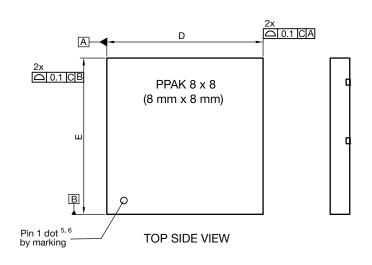
Fig. 20 - For N-Channel

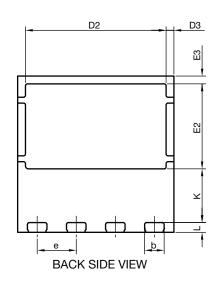
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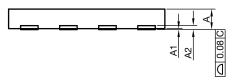


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PowerPAK® 8 x 8 Case Outline







| DIM. | MILLIMETERS | | | INCHES | | |
|------------------|-------------|------|-----------|--------------------|-------|-------|
| DIIVI. | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| Α | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |
| A1 | 0.00 | - | 0.05 | 0.000 | - | 0.002 |
| A2 | 020 ref. | | | 0.008 ref. | | |
| b | 0.95 | 1.00 | 1.05 | 0.037 | 0.039 | 0.041 |
| D | 7.90 | 8.00 | 8.10 | 0.311 | 0.315 | 0.319 |
| D2 | 7.10 | 7.20 | 7.30 | 0.280 | 0.283 | 0.287 |
| D3 | 0.40 BSC | | | 0.016 BSC | | |
| е | 2.00 BSC | | 0.079 BSC | | | |
| E | 7.90 | 8.00 | 8.10 | 0.311 | 0.315 | 0.319 |
| E2 | 4.30 | 4.35 | 4.40 | 0.169 | 0.171 | 0.173 |
| E3 | 0.40 BSC | | | 0.40 BSC 0.016 BSC | | |
| K | 2.75 BSC | | 0.108 BSC | | | |
| L | 0.45 | 0.50 | 0.55 | 0.018 | 0.020 | 0.022 |
| N ⁽³⁾ | 8 | | | | 8 | |

Notes

- (1) Use millimeters as the primary measurement
- (2) Dimensioning and tolerances conform to ASME Y14.5 M 1994
- (3) N is the number of terminals
- (4) The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body
- (5) Exact shape and size of this feature is optional

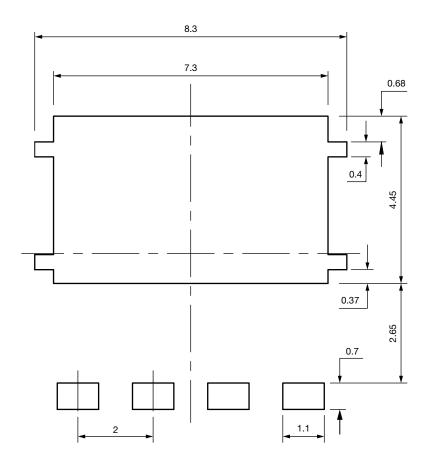
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DWG: 6041

Revision: 28-Sep-2020 1 Document Number: 67859



Recommended Minimum PADs for PowerPAK® 8 mm x 8 mm



Dimensions in millimeters



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